



SOT2169-1

HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 4.45 mm x 3.65 mm x 0.63 mm body

29 April 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HWFLGA36
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-12-2021
Manufacturer package code	98ASA01859D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.45	-	mm
package width	-	3.65	-	mm
seated height	-	0.63	0.687	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	



HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 4.45 mm x 3.65 mm x 0.63 mm body

2 Package outline

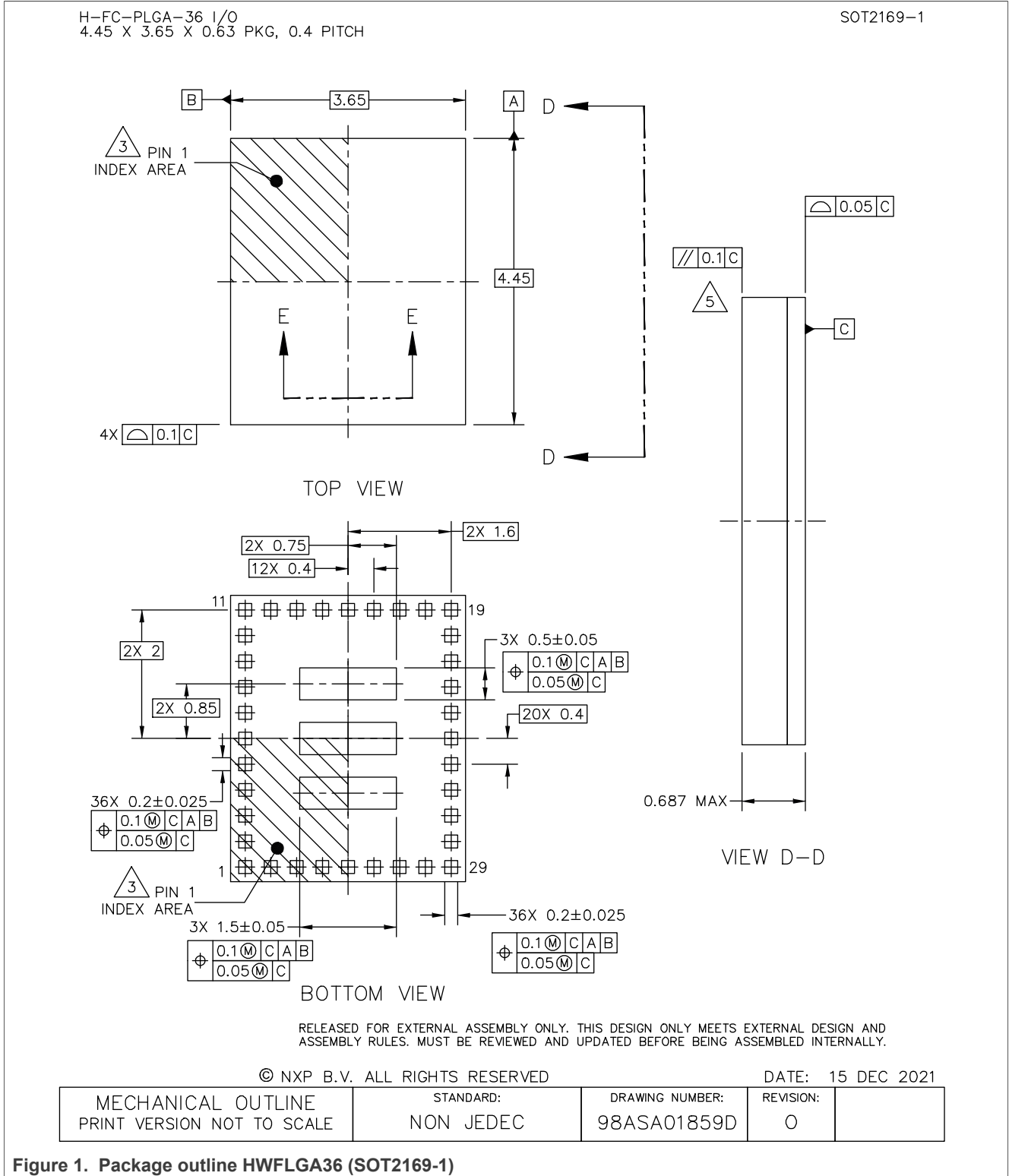
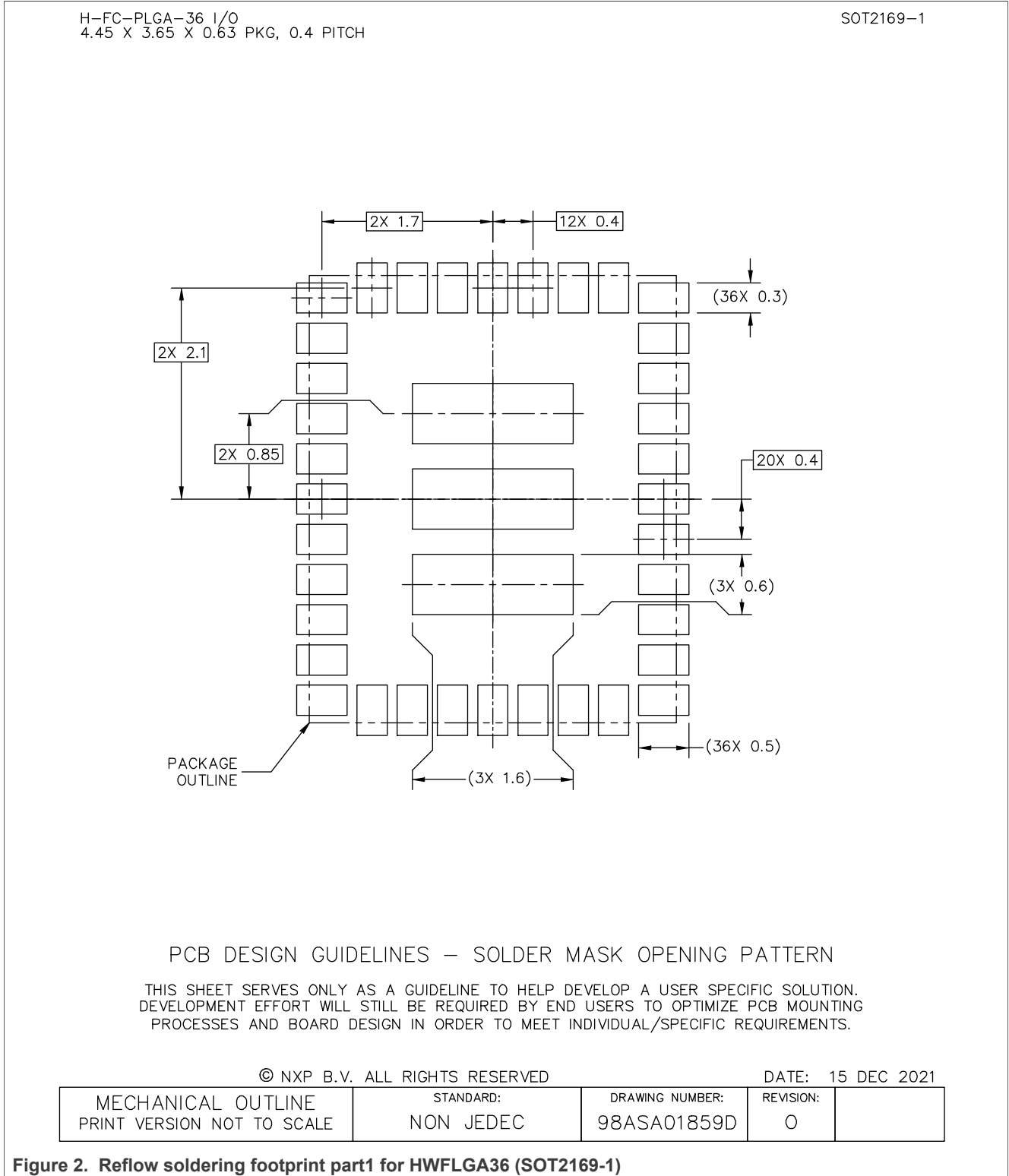


Figure 1. Package outline HWFLGA36 (SOT2169-1)

HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 4.45 mm x 3.65 mm x 0.63 mm body

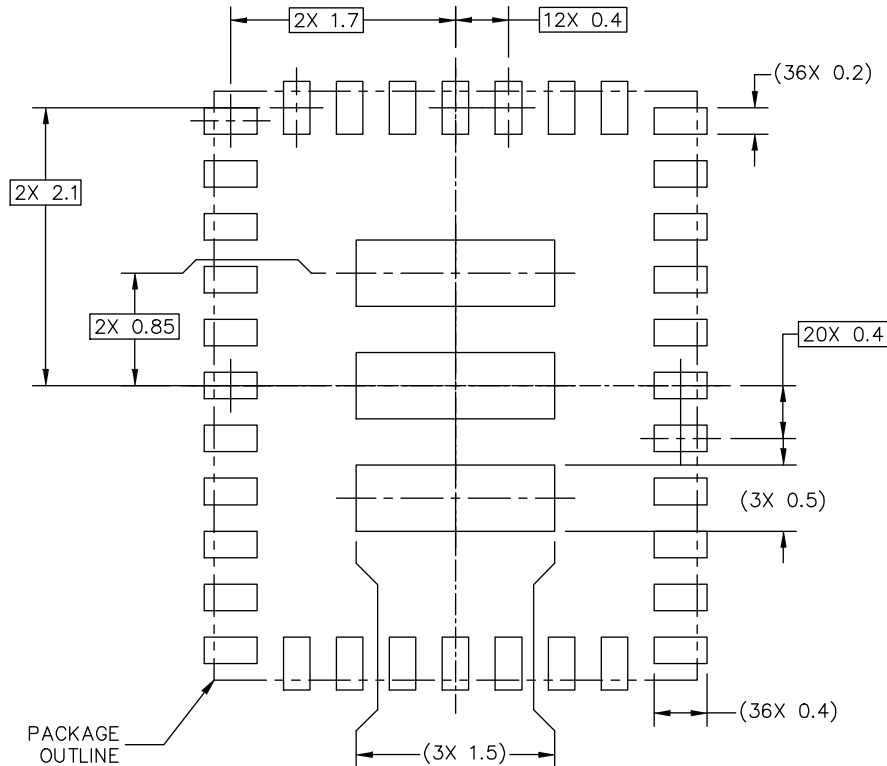
3 Soldering



HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 4.45 mm x 3.65 mm x 0.63 mm body

H-FC-PLGA-36 I/O
4.45 X 3.65 X 0.63 PKG, 0.4 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DATE: 15 DEC 2021

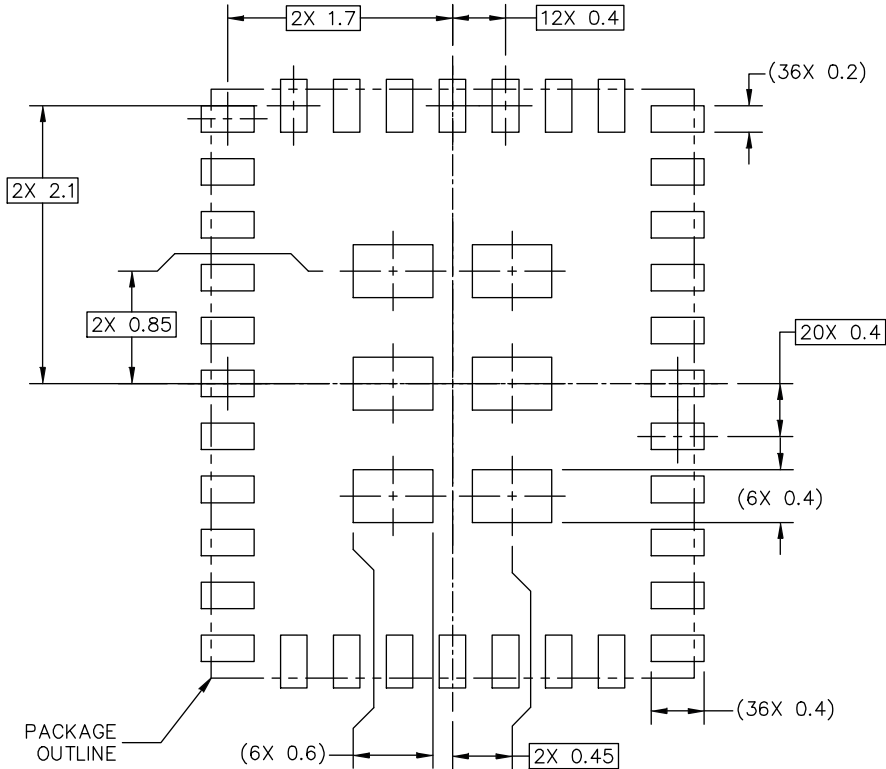
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01859D	REVISION: 0
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Figure 3. Reflow soldering footprint part2 for HWFLGA36 (SOT2169-1)

HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 4.45 mm x 3.65 mm x 0.63 mm body

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for HWFLGA36 (SOT2169-1)

**HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch,
4.45 mm x 3.65 mm x 0.63 mm body**

H-FC-PLGA-36 I/O
4.45 X 3.65 X 0.63 PKG, 0.4 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE

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Figure 5. Package outline note HWFLGA36 (SOT2169-1)

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4 Legal information

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